

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2777537

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
CHIA-PIN CHIU	03/10/2014
KINYA ICHIKAWA	03/13/2014
YOSHIHIRO TOMITA	03/13/2014
ROBERT L SANKMAN	03/11/2014
ERIC LI	03/18/2014
RECEIVING PARTY DATA	
Name:	INTEL CORPORATION
Street Address:	2200 MISSION COLLEGE BLVD.
City:	SANTA CLARA
State/Country:	CALIFORNIA
Postal Code:	95054
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14219749
CORRESPONDENCE DATA	
Fax Number:	
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Phone:	612-373-6900
Email:	request@slwip.com
Correspondent Name:	SCHWEGMAN, LUNDBERG & WOESSNER/INTEL
Address Line 1:	PO BOX 2938
Address Line 4:	MINNEAPOLIS, MINNESOTA 55402
ATTORNEY DOCKET NUMBER:	884.Q27US1
NAME OF SUBMITTER:	NANCY CUNDALL
SIGNATURE:	/Nancy Cundall/
DATE SIGNED:	03/20/2014
Total Attachments: 9	
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RECORDATION FORM COVER SHEET
PATENTS ONLY

Atty Ref/Docket No.: 884.Q27US1

Patent and Trademark Office

To the Director of the U.S. Patent and Trademark Office: Please record the attached original documents or copy thereof.

1. Name of conveying party(ies):

Chia-Pin Chiu, Kinya Ichikawa, Yoshihiro Tomita,
Robert L. Sankman, Eric Li

Additional name(s) of conveying party(ies) attached?

Yes No

3. Nature of conveyance:

Assignment Merger
 Security Agreement Change of Name
 Other

Execution Date: March 10, 2014, March 13, 2014,
March 13, 2014, March 11, 2014, March 18, 2014

2. Name and address of receiving party(ies):

Name: Intel Corporation

Street Address: 2200 Mission College Blvd.

City: Santa Clara State: CA Zip: 95054
Country: United States of America

Additional name(s) & address(es) attached? Yes No

4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. Patent Application No.(s)

Serial No. 14/219,749

B. Patent No.(s)

Additional numbers attached? Yes No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: Andrew R. Peret

Address:

Schwegman, Lundberg & Woessner, P.A.
P.O. Box 2938
Minneapolis, MN 55402--0938

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 3.41): \$ 0.00

Enclosed

Authorized to be charged to deposit account 19-0743

8. Please charge any additional fees or credit any over payments to our Deposit Account No.: 19-0743

DO NOT USE THIS SPACE

9. Statement and signature.

To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

Andrew R. Peret/Reg. No. 41,246

Name of Person Signing

Andrew Peret

Signature

March 20, 2014

Date

Total number of pages including cover sheet: 9

Mail documents to be recorded with required cover sheet information to:

Commissioner of Patents and Trademarks
Mail Stop Assignment Recordation Services
P.O. Box 1450
Alexandria, VA 22313-1450

PATENT
REEL: 032486 FRAME: 0155

ASSIGNMENT

In consideration of good and valuable consideration, the receipt of which is hereby acknowledged, we, the undersigned inventor(s):

<Chia-Pin Chiu, Kinya Ichikawa, Yoshihiro Tomita, Robert L. Sankman, Eric Li>

hereby sell, assign, and transfer to:

Intel Corporation

a corporation of Delaware, having a principal place of business at 2200 Mission College Boulevard, Santa Clara, California, 95054 USA ("Assignee"), and its successors, assigns, and legal representatives, the entire right, title, and interest for the United States and all other countries, in and to any and all inventions and improvements that are disclosed in the application for the patent entitled:

METHODS OF CONNECTING A FIRST ELECTRONIC PACKAGE

(I hereby authorize and request any attorney having appropriate authority from the assignee to insert on the designated lines below, the filing date and application number of said application when known.)

which was filed on March 19, 2014 as

United States of America Application Number 14/219,749
Country or International Office

which has been executed by the undersigned prior hereto or concurrently herewith on the date(s) indicated below,

and in and to said application and all Additional Applications, and all other patent applications that have been or shall be filed in the United States and all other countries and international filing offices on any of said inventions and improvements; and in and to all original and reissued patents that have been or shall be issued in the United States and all other countries and international filing offices on said inventions and improvements; and in and to all rights of priority resulting from the filing of said applications; as used herein "Additional Applications" includes but is not limited to design, utility, utility model, divisional, continuing, continuation-in-part, substitute, renewal, reissue, and national phase applications on said inventions and improvements;

and agree that said Assignee may apply for and receive a patent or patents for said inventions and improvements in its own name; and that, when requested, without charge to, but at the expense of, said Assignee, its successors, assigns, and legal representatives, to carry out in good faith the intent and purpose of this Assignment, the undersigned will execute all Additional Applications, and all other patent applications on any and all said inventions and improvements; execute all rightful oaths, assignments, powers of attorney, and other papers; communicate to said Assignee, its successors,

assigns, and legal representatives all facts known to the undersigned relating to said inventions and improvements and the history thereof; and generally assist said Assignee, its successors, assigns, or legal representatives in securing and maintaining proper patent protection for said inventions and improvements and for vesting title to said inventions and improvements, and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns, and legal representatives; and

covenant with said Assignee, its successors, assigns, and legal representatives that no assignment, grant, mortgage, license, or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.



Chia-Pin Chiu

3-10-2014

Date Signed

Kinya Ichikawa

Date Signed

Yoshihiro Tomita

Date Signed

Robert L. Sankman

Date Signed

Eric Li

Date Signed

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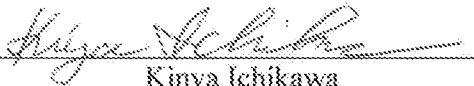
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Chia-Pin Chiu

Date Signed



Kinya Ichikawa

3/13/2014

Date Signed



Yoshihiro Tomita

3/13/2014

Date Signed

Robert L. Sankman

Date Signed

Eric Li

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Chia-Pin Chiu

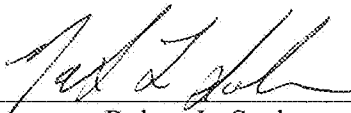
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Date Signed

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Robert L. Sankman

3/11/2014

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Date Signed

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Chia-Pin Chiu

Date Signed

Kinya Ichikawa

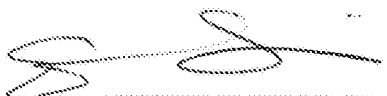
Date Signed

Yoshihiro Tomita

Date Signed

Robert L. Sankman

Date Signed



Eric Li

03/18/2014

Date Signed